

Maximum Ratings @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Non-Repetitive Peak Reverse Voltage	V _{RM}	100	V
Peak Repetitive Reverse Voltage	V _{RRM}	80	V
Working Peak Reverse Voltage	V _{RWM}		
DC Blocking Voltage	V _R		
RMS Reverse Voltage	V _{R(RMS)}	57	V
Forward Continuous Current (Note 5)	I _{FM}	500	mA
Average Rectified Output Current (Note 5)	I _O	250	mA
Non-Repetitive Peak Forward Surge Current	I _{FSM}	4.0	A
		1.0	

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P _D	200	mW
Thermal Resistance Junction to Ambient Air (Note 5)	R _{θJA}	625	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +150	°C

Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 6)	V _{(BR)R}	80	—	V	I _R = 2.5μA
Forward Voltage	V _F	0.62	0.72	V	I _F = 5.0mA
		—	0.855		I _F = 10mA
		—	1.0		I _F = 100mA
		—	1.25		I _F = 150mA
Peak Reverse Current (Note 6)	I _R	—	100	nA	V _R = 70V
			50	μA	V _R = 75V, T _J = 150°C
			30	μA	V _R = 25V, T _J = 150°C
			25	nA	V _R = 20V
Total Capacitance	C _T	—	3.5	pF	V _R = 6V, f = 1.0MHz
Reverse Recovery Time	t _{rr}	—	4.0	ns	V _R = 6V, I _F = 5mA

Notes: 5. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch; pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at <http://www.diodes.com>.
 6. Short duration pulse test used to minimize self-heating effect.

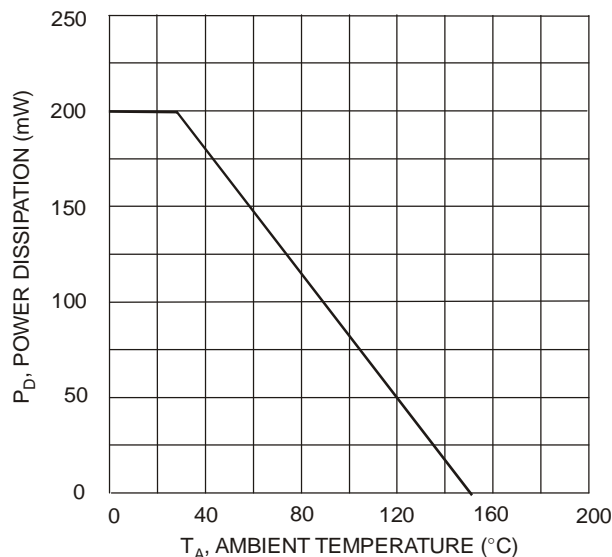


Fig. 1 Power Derating Curve (Note 5)

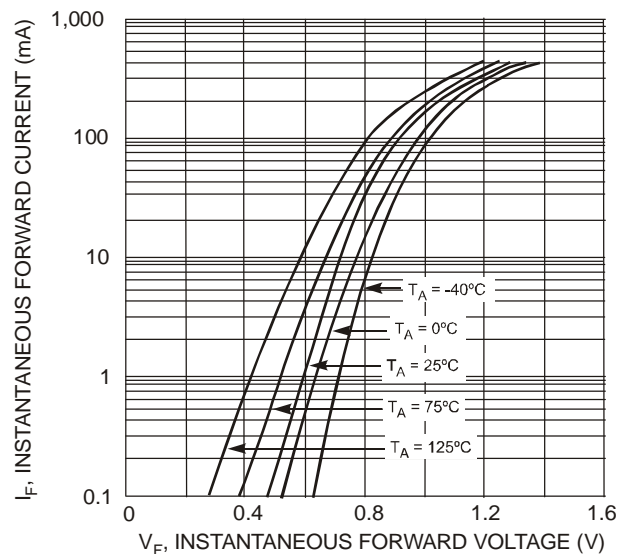


Fig. 2 Typical Forward Characteristics

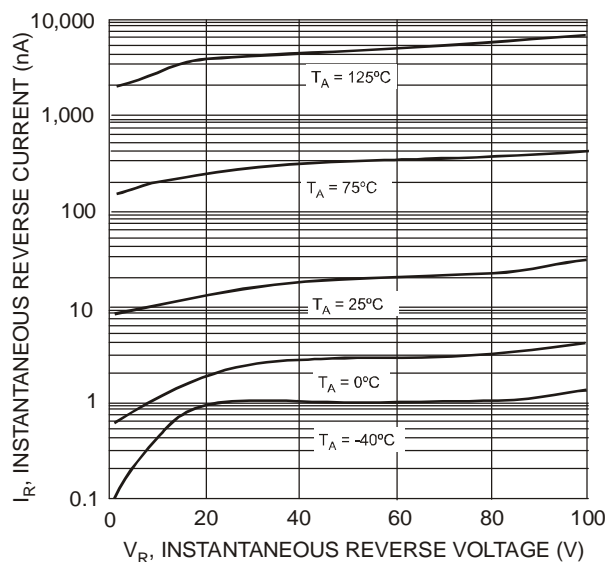


Fig. 3 Typical Reverse Characteristics

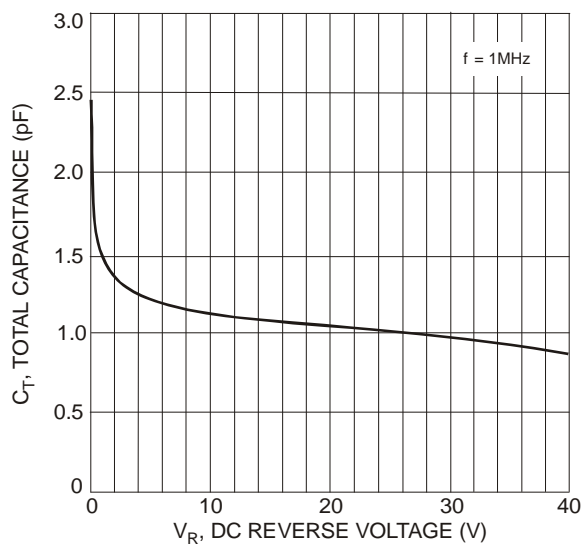
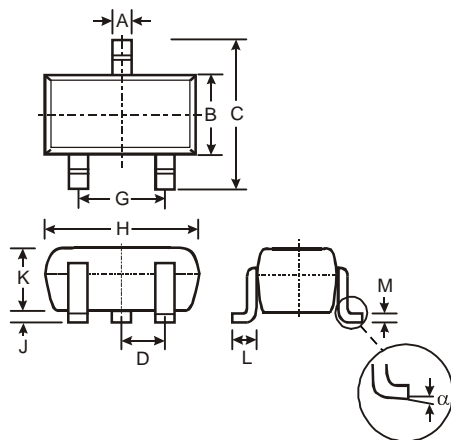


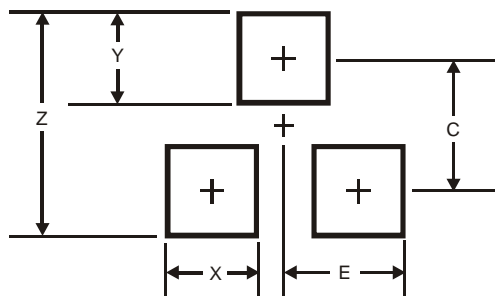
Fig. 4 Total Capacitance vs. Reverse Voltage

Package Outline Dimensions



SOT-323			
Dim	Min	Max	Typ
A	0.25	0.40	0.30
B	1.15	1.35	1.30
C	2.00	2.20	2.10
D	-	-	0.65
G	1.20	1.40	1.30
H	1.80	2.20	2.15
J	0.0	0.10	0.05
K	0.90	1.00	1.00
L	0.25	0.40	0.30
M	0.10	0.18	0.11
α	0°	8°	-
All Dimensions in mm			

Suggested Pad Layout



Dimensions	Value (in mm)
Z	2.8
X	0.7
Y	0.9
C	1.9
E	1.0

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